

Appl. No. 10/040,118

Amdt. dated November 8, 2004

Reply to Final Office Action of September 8, 2004

AMENDMENT TO THE CLAIMS**Claim 1 (cancelled)**

Claim 2 (previously presented): A method of filling holes in a substrate having a plurality of holes to be filled comprising:

providing an etched hole-fill stand-off comprising imaging a copper clad laminate with an image similar to that used to image a surface of the substrate, and subjecting the imaged laminate to develop-etch-strip processing to form a pattern in a copper surface of the laminate, the pattern having a plurality of holes, each of the plurality of holes corresponding to a hole to be filled of the substrate, the laminate holes being at least slightly larger in diameter than their corresponding substrate holes;

aligning the stand-off to a tooling plate;

aligning the substrate to the stand off and placing the substrate in contact with the stand-off; and

filling the plurality of the holes of the substrate.

Claim 3 (previously presented): The method of claim 2 further comprising filling the holes of the substrate with a fill material such that the fill material extends at least partially into the holes of the stand-off.

Claim 4 (original): The method of claim 3 further comprising removing the substrate from the stand-off wherein substantially all of the fill material extending into the stand-off remains after removal of the stand-off.

Claim 5 (cancelled)

Claim 6 (previously presented): A method of Claim 2 wherein filling the plurality of holes of the substrate utilizes a pressurized fill head while maintaining proper alignment between the plurality of holes in a substrate and holes of the stand-off.